ABSTRACT

SUBSTRATE CLEANING APPARATUS, SUBSTRATE CLEANING METHOD, AND STORAGE MEDIUM

To provide a substrate cleaning apparatus capable of effectively removing deposits adhering to at least an end surface of a substrate by means of a sponge-like brush. A substrate cleaning apparatus includes: a spin chuck 3 configured to rotatably hold a substrate W; a motor 4 configured to rotate the substrate W held by the spin chuck 3; a cleaning-liquid supply mechanism 10 configured to supply a cleaning liquid to the substrate W held by the spin chuck 3. The cleaning mechanism includes: a brush 21 made of a sponge-like resin, which is brought into contact with at least an end surface of the wafer W during the cleaning; and a brush compressing mechanism 23a, 23b, and 24 configured to compress the brush 21. The brush 21 is compressed by the compressing mechanism 23a, 23b, and 24, and cleans at least the end surface of the substrate W.

FIG. 3



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